

Description

The AP30N15D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 150V I_{D} = 30 A$

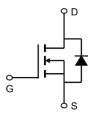
 $R_{DS(ON)}$ < $52m\Omega$ @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

•	ackage marking and Ordering information						
Ī	Product ID	Pack	Marking	Qty(PCS)			
Ī	AP30N15D	TO-252-3L	AP30N15D XXX YYYY	2500			

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	150	V	
VGS	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current ¹	30	А	
$I_D@T_C=100^{\circ}C$	Continuous Drain Current ¹	16	А	
$I_D@T_A=25^{\circ}C$	Continuous Drain Current ¹	4.5	А	
I _D @T _A =70℃ Continuous Drain Current¹		3.8	А	
IDM	IDM Pulsed Drain Current ²		А	
P _D @T _C =25 °C Total Power Dissipation ³		72.6	W	
P _D @T _A =25℃ Total Power Dissipation ³		2.7	W	
TSTG	TSTG Storage Temperature Range		°C	
TJ	Operating Junction Temperature Range	-55 to 175	$^{\circ}$ C	
R₀JA	Thermal Resistance Junction-ambient ¹	55	°C/W	
R _θ JC Thermal Resistance Junction-Case ¹		2.0	°C/W	



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	e Breakdown Voltage V _{GS} =0V , I _D =250uA		165		V	
RDS(ON)	ON) Static Drain-Source On-Resistance ² V _{GS} =10V , I _D =			43	52	mΩ	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =10A		45	70	mΩ	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.8	2.5	V	
Ipss	Drain-Source Leakage Current	V _{DS} =120V , V _{GS} =0V , T _J =25°C			1	uA	
IDSS	Drain-Source Leakage Current	V _{DS} =120V , V _{GS} =0V , T _J =55°C			5		
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		25		S	
Qg	Total Gate Charge			23			
Qgs	Gate-Source Charge	V_{DS} =75 V , V_{GS} =10 V , I_{D} =10 A		5.8		nC	
Qgd	Gate-Drain Charge			4.2			
T _{d(on)}	Turn-On Delay Time			16.2			
Tr	Rise Time	V_{DD} =75V , V_{GS} =10V , R_{G} =3.3 Ω		18.6		ns	
T _d (off)	Turn-Off Delay Time	I _D =10A		28.5			
Tf	Fall Time	.5 .5 .		6.5			
Ciss	Input Capacitance			1190			
Coss	Output Capacitance	V_{DS} =75V , V_{GS} =0V , f=1MHz		73		pF	
Crss	Reverse Transfer Capacitance			4			
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			20	Α	
VsD	Diode Forward Voltage² V _{GS} =0V , I _S =1A , T _J =25℃				1.2	V	
trr	Reverse Recovery Time IF=10A, dI/dt=100A/µs,			45		nS	
Qrr	Q _{rr} Reverse Recovery Charge T _J =25			138		nC	

Note:

^{1.}The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$

^{3.}The power dissipation is limited by 150°C junction temperature

^{4.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

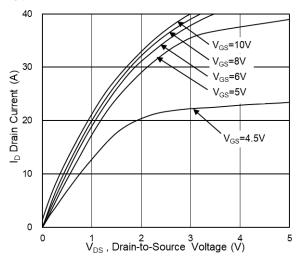


Fig.1 Typical Output Characteristics

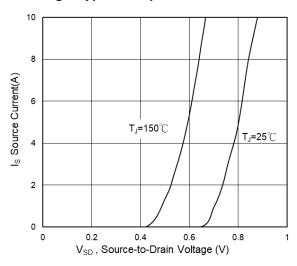


Fig.3 Source Drain Forward Characteristics

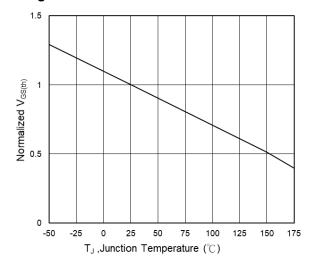


Fig.5 Normalized $V_{\text{GS(th)}}$ vs T_{J}

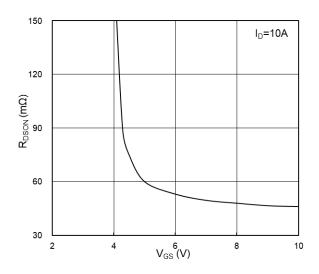


Fig.2 On-Resistance vs G-S Voltage

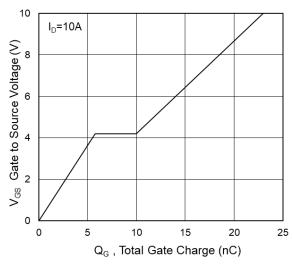


Fig.4 Gate-Charge Characteristics

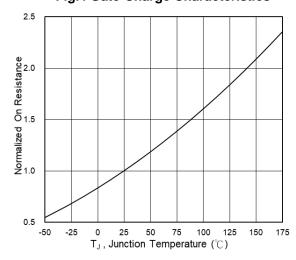
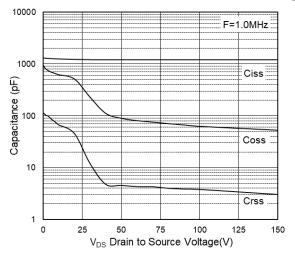


Fig.6 Normalized $R_{\text{DSON}}\,\text{vs}\,\,T_{\text{J}}$







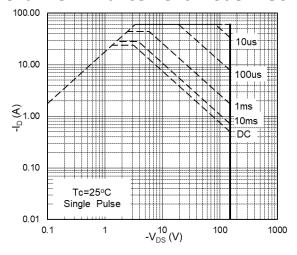


Fig.7 Capacitance

Fig.8 Safe Operating Area

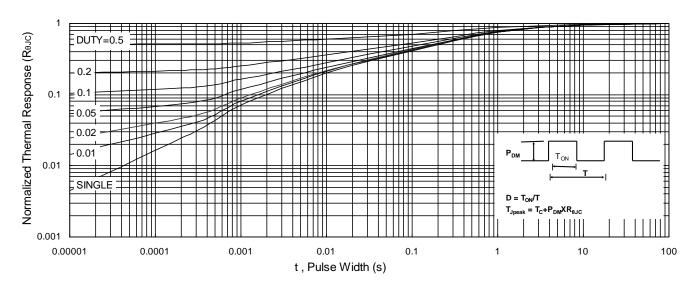


Fig.9 Normalized Maximum Transient Thermal Impedance

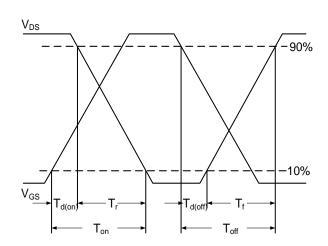


Fig.10 Switching Time Waveform

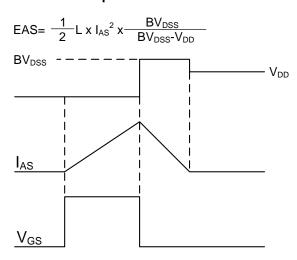
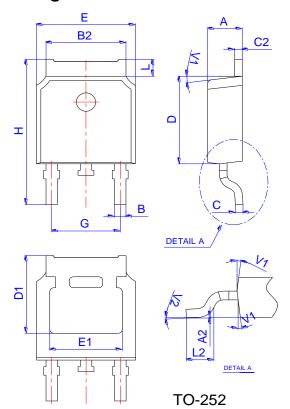


Fig.11 Unclamped Inductive Switching Waveform

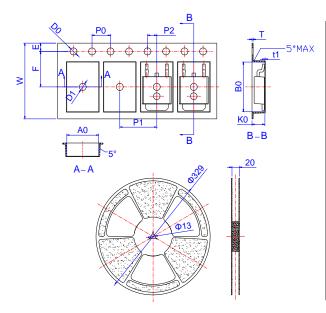


Package Mechanical Data: TO-252-3L



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202	0.216		
С	0.40		0.60	0.016	0.024		
C2	0.44		0.58	0.017	0.023		
D	5.90		6.30	0.232		0.248	
D1		5.30REF		0.209REF			
E	6.40		6.80	0.252	0.268		
E1	4.63			0.182			
G	4.47		4.67	0.176	0.184		
Н	9.50		10.70	0.374	0.421		
L	1.09		1.21	0.043	0.048		
L2	1.35		1.65	0.053	0.065		
V1		7°			7°		
V2	0°		6°	0°		6°	

Reel Spectification-TO-252



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
E	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
В0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
Т	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	



150V N-Channel Enhancement Mode MOSFET Attention

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Edition	Date	Change
Rve1.0	2020/9/11	Initial release

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